

## N-Channel Super Junction Power MOSFET IV

### General Description

The series of devices use advanced trench gate super junction technology and design to provide ultra-low  $R_{DS(ON)}$  and low gate charge and With a rapid recovery body diode. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, industrial power applications, Fast charger, new energy vehicle charging pile, on-board OBC etc.

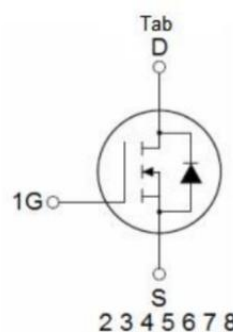
### Features

- New technology for high voltage device
- Ultra low on-resistance and ultra low conduction losses
- Ultra Low Gate Charge cause lower driving requirements
- Diode reverse recovery speed is super fast
- High reliability
- ROHS compliant & Halogen Free

### Application

- Power factor correction (PFC)
- Switched mode power supplies (SMPS)
- Uninterruptible Power Supply (UPS)
- On-board charger (OBC)

$V_{DS\ min@T_{jmax}}$	710	V
$R_{DS(ON)TYP}$	110	mΩ
$I_D$	26	A
$Q_g$	41	nC



Schematic diagram

✧ Intrinsic fast-recovery body diode

### Package Marking And Ordering Information

Device	Device Package	Marking
NCE65NF130LL	TOLL-8L	NCE65NF130LL



TOLL-8L

Table 1. Absolute Maximum Ratings ( $T_c=25^\circ\text{C}$ )

Parameter	Symbol	Value	Unit
Drain-Source Voltage ( $V_{GS}=0V$ )	$V_{DS}$	650	V
Gate-Source Voltage ( $V_{DS}=0V$ ) AC ( $f>1\text{ Hz}$ )	$V_{GS}$	$\pm 30$	V
Gate-Source Voltage ( $V_{DS}=0V$ ) DC	$V_{GS}$	$\pm 20$	V
Continuous Drain Current at $T_c=25^\circ\text{C}$	$I_D (DC)$	26	A
Continuous Drain Current at $T_c=100^\circ\text{C}$	$I_D (DC)$	18.2	A
Pulsed drain current (Note 1)	$I_{DM (pluse)}$	78	A
Maximum Power Dissipation ( $T_c=25^\circ\text{C}$ )	$P_D$	237	W
Derate above $25^\circ\text{C}$		1.58	W/ $^\circ\text{C}$
Avalanche current (Note 1)	$I_{AS}$	7	A
Drain Source voltage slope, $V_{DS} \leq 480\text{ V}$ ,	$dv/dt$	50	V/ns
Reverse diode $dv/dt$ , $V_{DS} \leq 480\text{ V}$ , $I_{SD} < I_D$	$dv/dt$	50	V/ns
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55...+175	$^\circ\text{C}$

\* limited by maximum junction temperature

**Table 2. Thermal Characteristic**

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case (Maximum)	$R_{thJC}$	0.63	$^{\circ}\text{C}/\text{W}$
Thermal Resistance, Junction-to-Ambient (Maximum)	$R_{thJA}$	62	$^{\circ}\text{C}/\text{W}$

**Table 3. Electrical Characteristics (TA=25°C unless otherwise noted)**

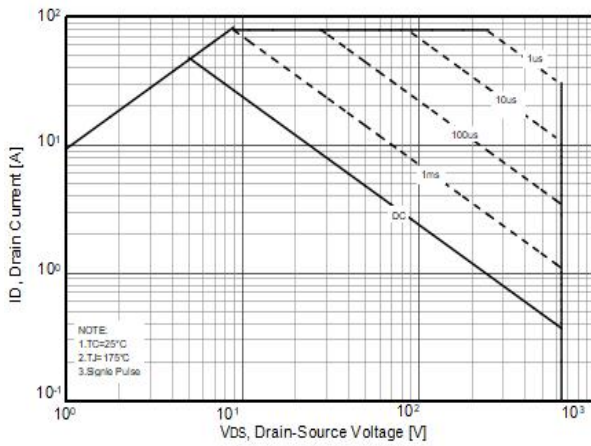
Parameter	Symbol	Condition	Min	Typ	Max	Unit
On/off states						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =250uA	650			V
Zero Gate Voltage Drain Current(Tc=25℃)	I <sub>DSS</sub>	V <sub>DS</sub> =650V,V <sub>GS</sub> =0V			10	μA
Zero Gate Voltage Drain Current(Tc=125℃)	I <sub>DSS</sub>	V <sub>DS</sub> =650V,V <sub>GS</sub> =0V			400	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V,V <sub>DS</sub> =0V			±100	nA
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =500uA	3.5	4.2	5.0	V
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =13A		110	130	mΩ
Dynamic Characteristics						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =50V,V <sub>GS</sub> =0V, F=1.0MHz		2161		pF
Output Capacitance	C <sub>oss</sub>			95		pF
Reverse Transfer Capacitance	C <sub>rss</sub>			50		pF
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =480V,I <sub>D</sub> =13A, V <sub>GS</sub> =10V		41.2		nC
Gate-Source Charge	Q <sub>gs</sub>			16.3		nC
Gate-Drain Charge	Q <sub>gd</sub>			12.8		nC
Gate plateau voltage	V <sub>gp</sub>			7.0		V
Intrinsic gate resistance	R <sub>G</sub>	f = 1 MHz open drain		1.5		Ω
Switching times						
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> =380V,I <sub>D</sub> =13A, R <sub>G</sub> =1.7Ω,V <sub>GS</sub> =10V		43		nS
Turn-on Rise Time	t <sub>r</sub>			16		nS
Turn-Off Delay Time	t <sub>d(off)</sub>			93		nS
Turn-Off Fall Time	t <sub>f</sub>			20		nS
Source- Drain Diode Characteristics						
Source-drain current(Body Diode)	I <sub>SD</sub>	T <sub>C</sub> =25℃			26	A
Pulsed Source-drain current(Body Diode)	I <sub>SDM</sub>				78	A
Forward On Voltage	V <sub>SD</sub>	T <sub>j</sub> =25℃,I <sub>SD</sub> =26A,V <sub>GS</sub> =0V		1.0	1.2	V
Reverse Recovery Time	t <sub>rr</sub>	T <sub>j</sub> =25℃,I <sub>F</sub> =13A,di/dt=100A/μs		145		nS
Reverse Recovery Charge	Q <sub>rr</sub>			0.725		uC
Peak Reverse Recovery Current	I <sub>rrm</sub>			10		A

Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature

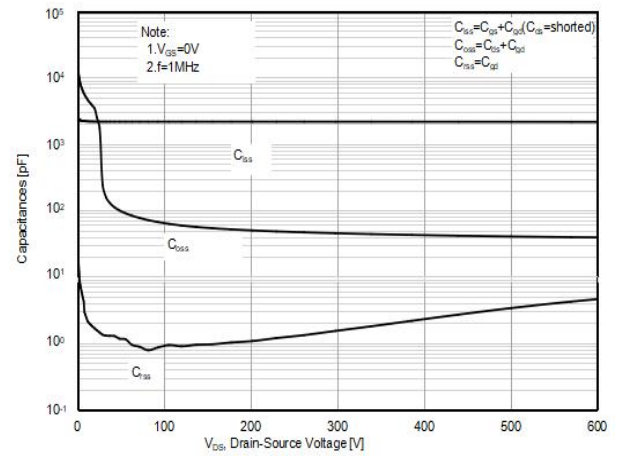
2.  $T_j=25^{\circ}\text{C}, V_{DD}=50V, V_G=10V, R_G=25\Omega$

## TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (curves)

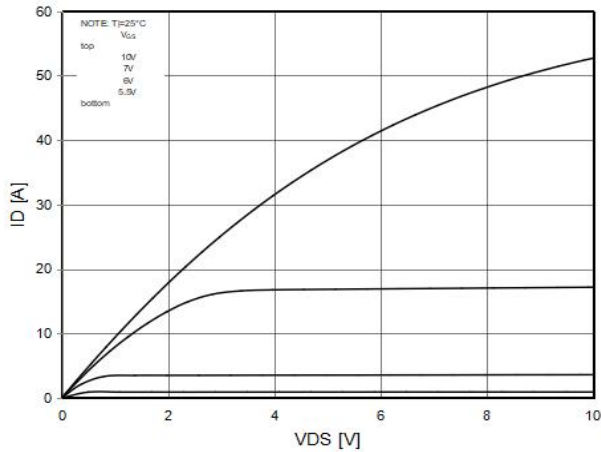
**Figure1. Safe operating area**



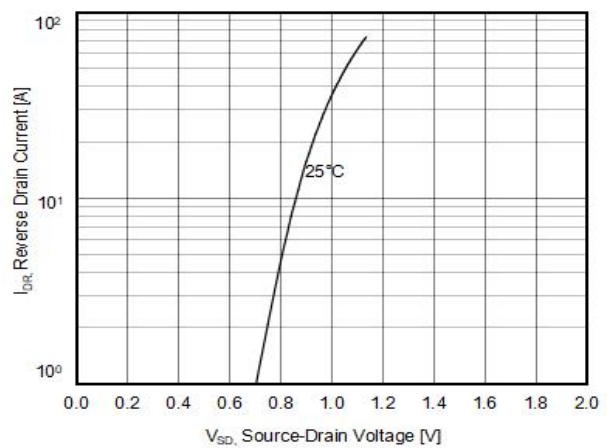
**Figure2. Capacitance**



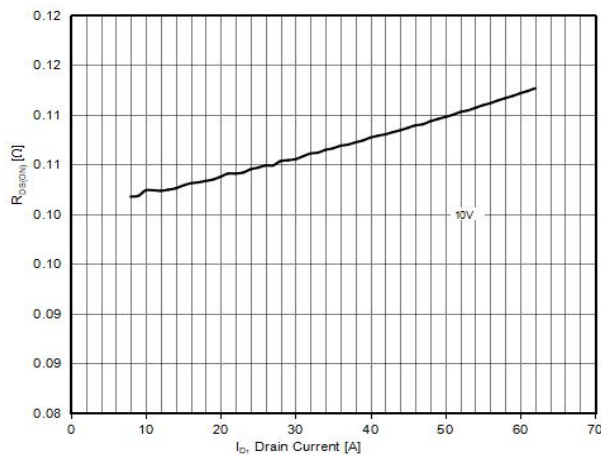
**Figure3. Output characteristics**



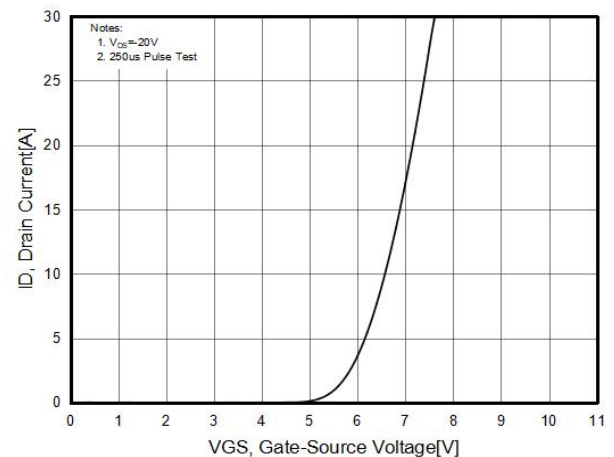
**Figure4. Source-Drain Diode Forward Voltage**



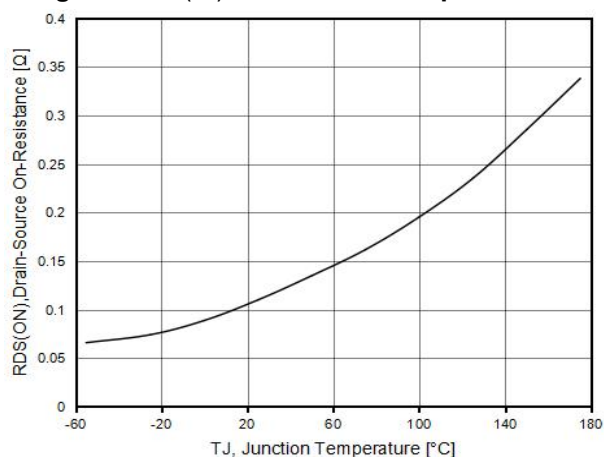
**Figure5. Static drain-source on resistance**



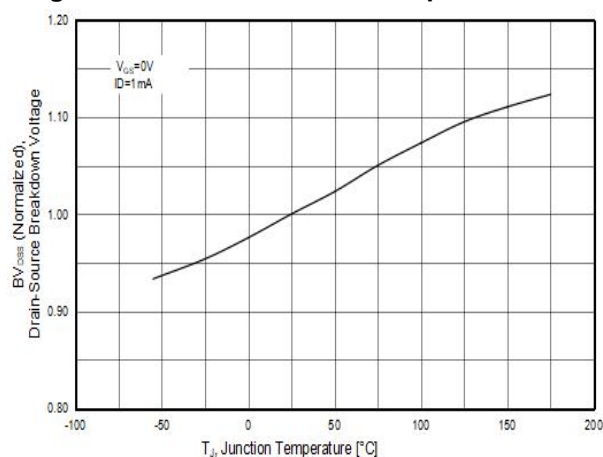
**Figure6. Transfer characteristics**



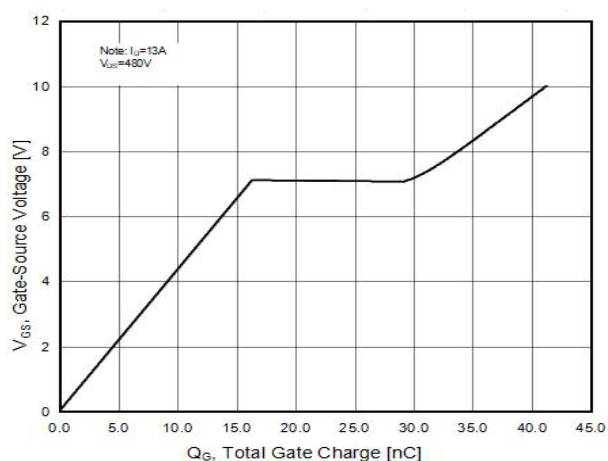
**Figure7.  $R_{DS(ON)}$  vs Junction Temperature**



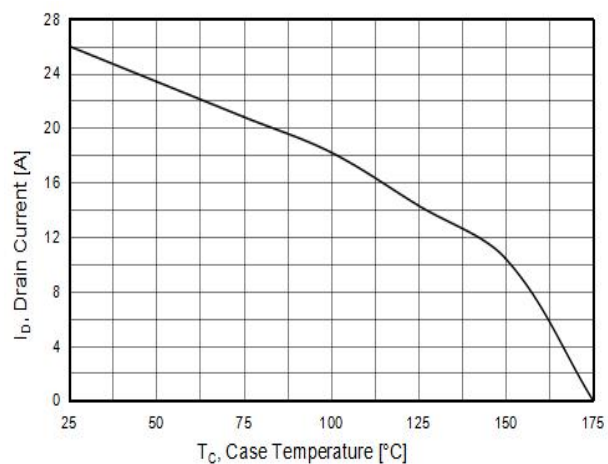
**Figure8.  $BV_{DSS}$  vs Junction Temperature**



**Figure9. Gate charge waveforms**

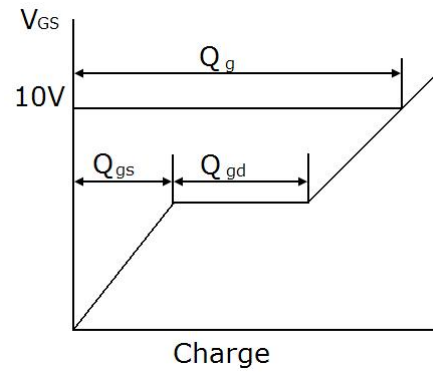
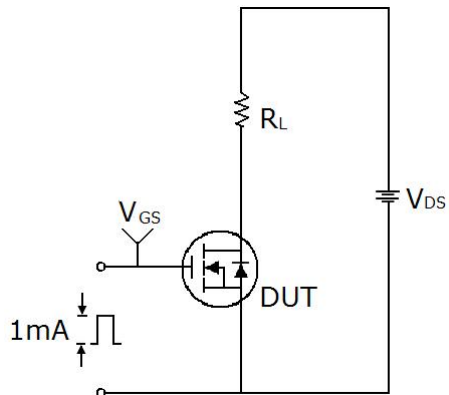


**Figure10. Maximum  $I_D$  vs Junction Temperature**

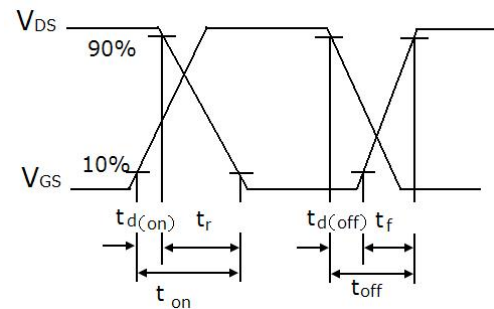
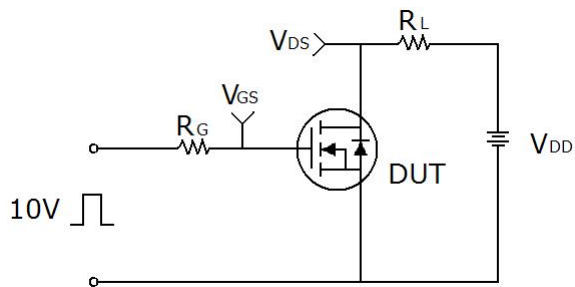


## Test circuit

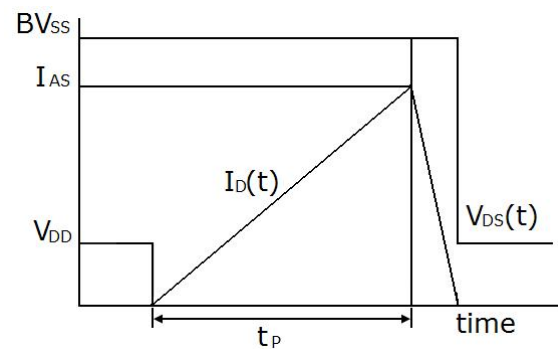
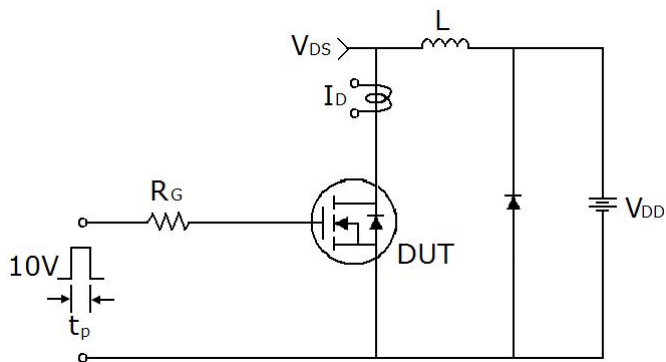
### 1) Gate charge test circuit & Waveform



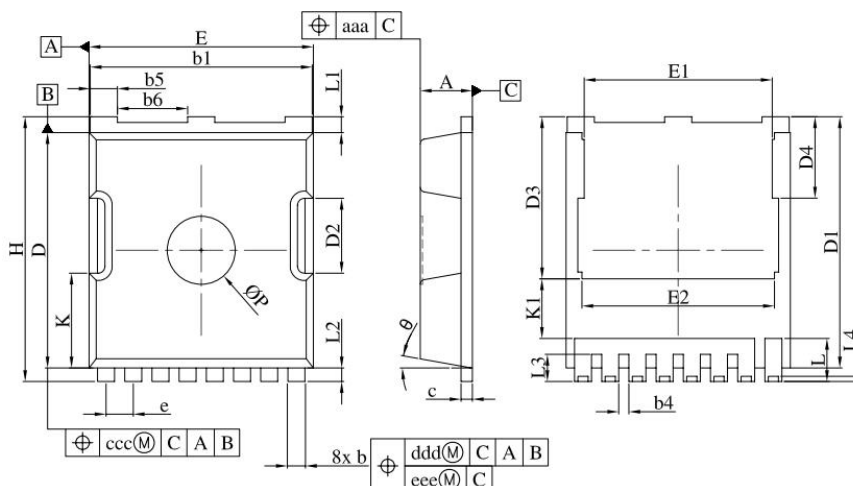
### 2) Switch Time Test Circuit:



### 3) Unclamped Inductive Switching Test Circuit & Waveforms



## TOLL-8L Package Information



SYMBOL	Dimensions In Millimeters			Dimensions In Inches		
	Min	Typ	Max	Min	Typ	Max
A	2.20	2.30	2.40	0.087	0.091	0.094
b	0.70	0.80	0.90	0.028	0.031	0.035
b1	9.70	9.80	9.90	0.382	0.386	0.390
b4	0.30	0.40	0.50	0.012	0.016	0.020
b5	1.10	1.20	1.30	0.043	0.047	0.051
b6	3.00	3.10	3.20	0.118	0.122	0.126
c	0.40	0.50	0.60	0.016	0.020	0.024
D	10.28	10.38	10.55	0.405	0.409	0.415
D1	10.98	11.08	11.18	0.432	0.436	0.440
D2	3.20	3.30	3.40	0.126	0.130	0.134
D3	7.00	7.15	7.30	0.276	0.281	0.287
D4	3.44	3.59	3.74	0.135	0.141	0.147
e	1.10	1.20	1.30	0.043	0.047	0.051
E	9.80	9.90	10.00	0.386	0.390	0.394
E1	8.20	8.30	8.40	0.323	0.327	0.331
E2	8.35	8.50	8.65	0.329	0.335	0.341
H	11.50	11.68	11.85	0.453	0.460	0.467
K	4.08	4.18	4.28	0.161	0.165	0.169
K1	2.45	--	--	0.096	--	--
L	1.60	1.90	2.10	0.063	0.075	0.083
L1	0.50	0.70	0.90	0.020	0.028	0.035
L2	0.50	0.60	0.70	0.020	0.024	0.028
L3	1.00	1.20	1.30	0.039	0.047	0.051
L4	0.13	0.23	0.33	0.005	0.009	0.013
P	2.85	3.00	3.15	0.112	0.118	0.124

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